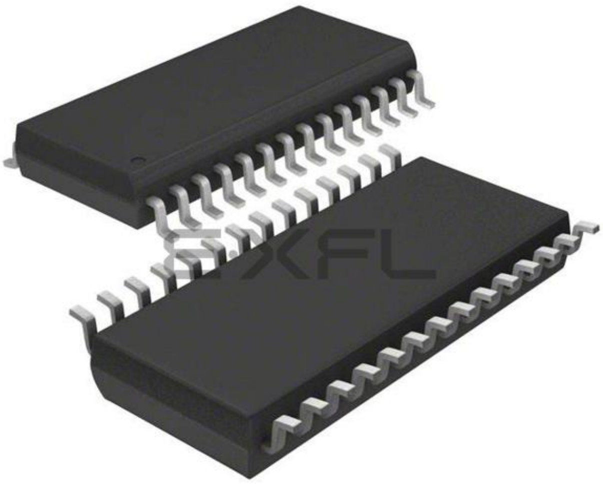


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I²C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 8x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4124pvi-442t

More Information

Cypress provides a wealth of data at www.cypress.com to help you to select the right PSoC device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources, see the knowledge base article KBA86521, How to Design with PSoC 3, PSoC 4, and PSoC 5LP. Following is an abbreviated list for PSoC 4:

- Overview: PSoC Portfolio, PSoC Roadmap
- Product Selectors: PSoC 1, PSoC 3, PSoC 4, PSoC 5LP
  In addition, PSoC Creator includes a device selection tool.
- Application notes: Cypress offers a large number of PSoC application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with PSoC 4 are:
  - AN79953: Getting Started With PSoC 4
  - AN88619: PSoC 4 Hardware Design Considerations
  - AN86439: Using PSoC 4 GPIO Pins
  - AN57821: Mixed Signal Circuit Board Layout
  - AN81623: Digital Design Best Practices
  - AN73854: Introduction To Bootloaders
  - AN89610: ARM Cortex Code Optimization
  - AN90071: CY8CMBRxxx CapSense Design Guide
- Technical Reference Manual (TRM) is in two documents:
  - Architecture TRM details each PSoC 4 functional block.
  - Registers TRM describes each of the PSoC 4 registers.
- Development Kits:
  - CY8CKIT-042, PSoC 4 Pioneer Kit, is an easy-to-use and inexpensive development platform. This kit includes connectors for Arduino™ compatible shields and Digilent® Pmod™ daughter cards.
  - CY8CKIT-049 is a very low-cost prototyping platform. It is a low-cost alternative to sampling PSoC 4 devices.
  - CY8CKIT-001 is a common development platform for any one of the PSoC 1, PSoC 3, PSoC 4, or PSoC 5LP families of devices.

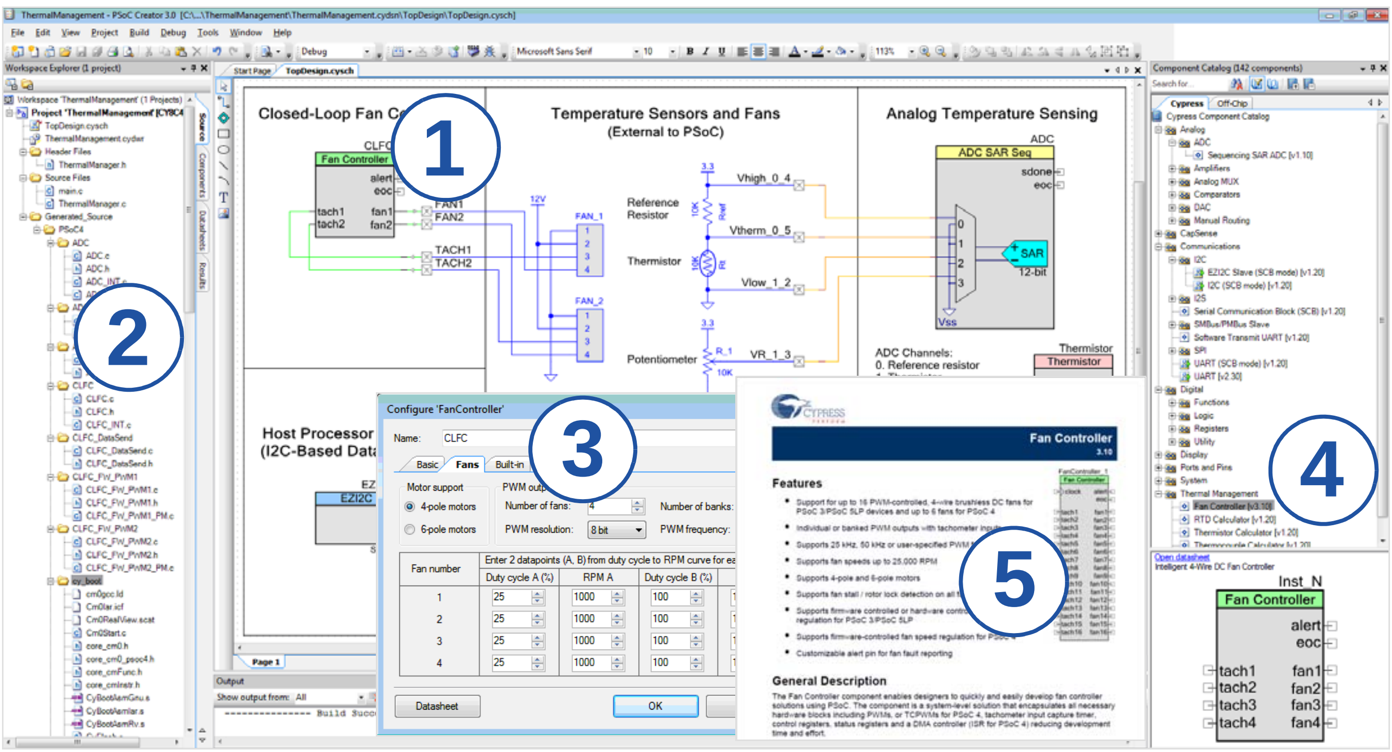
The MiniProg3 device provides an interface for flash programming and debug.

PSoC Creator

PSoC Creator is a free Windows-based Integrated Design Environment (IDE). It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, and PSoC 5LP based systems. Create designs using classic, familiar schematic capture supported by over 100 pre-verified, production-ready PSoC Components; see the list of component datasheets. With PSoC Creator, you can:

1. Drag and drop component icons to build your hardware system design in the main design workspace
2. Codesign your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
3. Configure components using the configuration tools
4. Explore the library of 100+ components
5. Review component datasheets

Figure 1. Multiple-Sensor Example Project in PSoC Creator



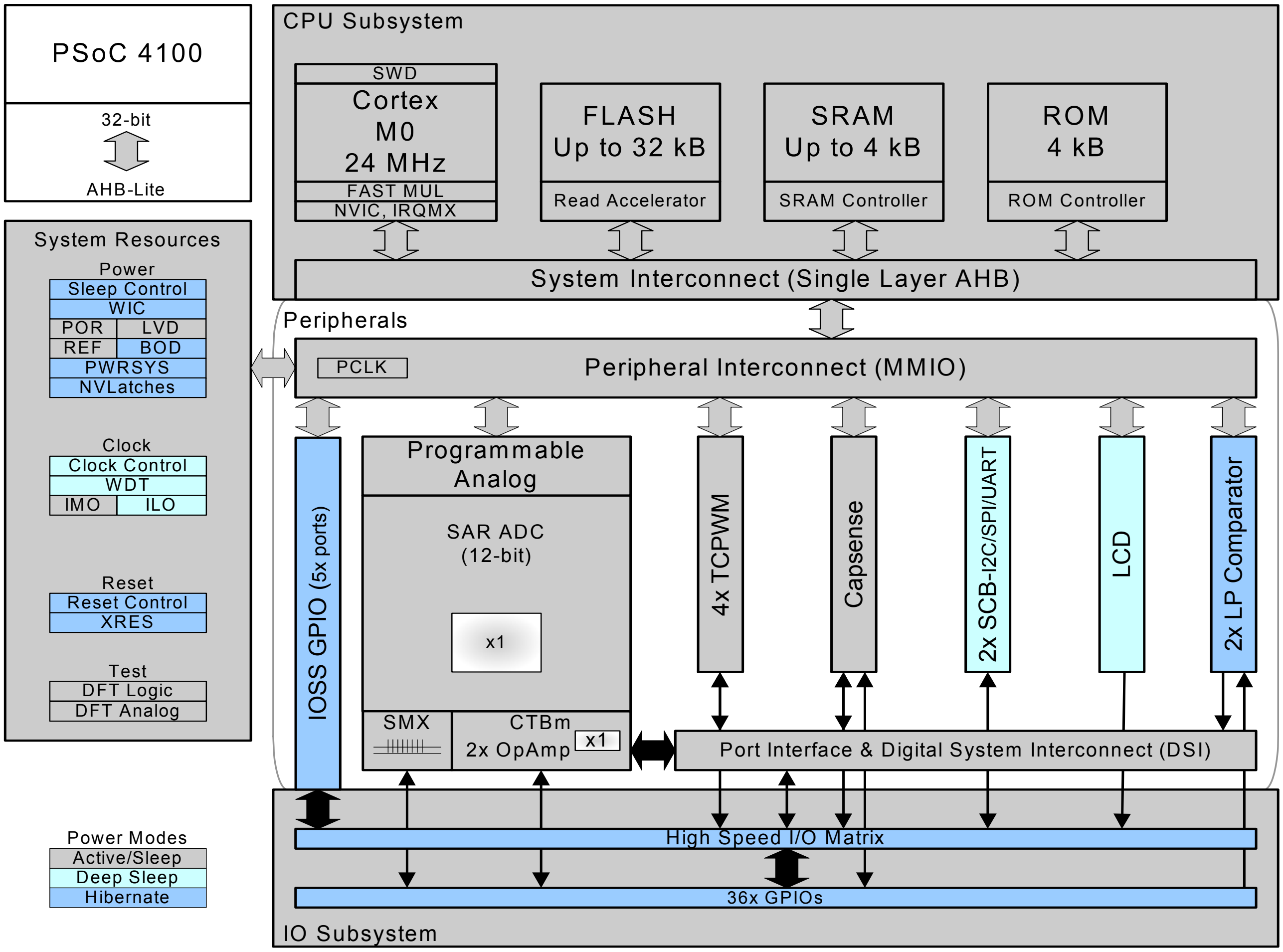


Figure 2. Block Diagram

The PSoC 4100 devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial_Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator Integrated Development Environment (IDE) provides fully integrated programming and debug support for the PSoC 4100 devices. The SWD interface is fully compatible with industry standard third party tools. With the ability to disable debug features, with very robust flash protection, and by allowing customer-proprietary functionality to be implemented in on-chip programmable blocks, the PSoC 4100 family provides a level of security not possible with multi-chip application solutions or with microcontrollers.

The debug circuits are enabled by default and can only be disabled in firmware. If not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. Because all programming, debug, and test interfaces are disabled when maximum device security is enabled, PSoC 4100 with device security enabled may not be returned for failure analysis. This is a trade-off the PSoC 4100 allows the customer to make.

IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4100. It is trimmed during testing to achieve the specified accuracy. Trim values are stored in nonvolatile latches (NVL). Additional trim settings from flash can be used to compensate for changes. The IMO default frequency is 24 MHz and it can be adjusted between 3 MHz to 24 MHz in steps of 1 MHz. The IMO tolerance with Cypress-provided calibration settings is ±2%.

ILO Clock Source

The ILO is a very low power oscillator, which is primarily used to generate clocks for peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the timeout occurs. The watchdog reset is recorded in the Reset Cause register.

Reset

PSoC 4100 can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset to avoid complications with configuration and multiple pin functions during power-on or reconfiguration. The XRES pin has an internal pull-up resistor that is always enabled.

Voltage Reference

The PSoC 4100 reference system generates all internally required references. A 1% voltage reference spec is provided for the 12-bit ADC. To allow better signal to noise ratios (SNR) and better absolute accuracy, it is possible to bypass the internal reference using a GPIO pin or to use an external reference for the SAR.

Analog Blocks

12-bit SAR ADC

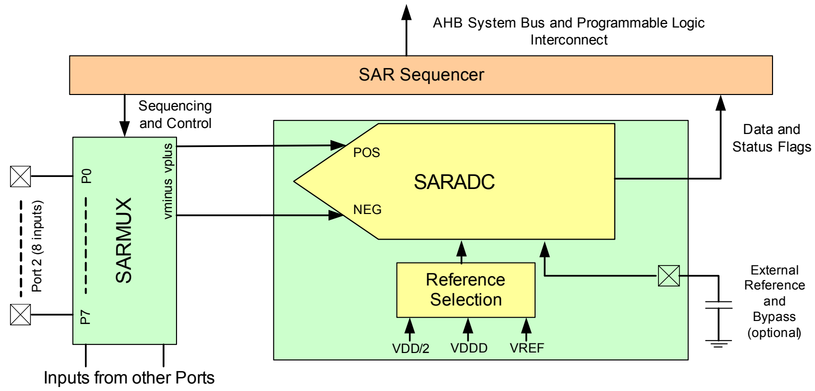
The 12-bit 806 ksps SAR ADC can operate at a maximum clock rate of 14.5 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The block functionality is augmented for the user by adding a reference buffer to it (trimmable to ±1%) and by providing the choice (for the PSoC 4100 case) of three internal voltage references: V_{DD}, $V_{DD}/2$, and V_{REF} (nominally 1.024 V) as well as an external reference through a GPIO pin. The sample-and-hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. System performance will be 65 dB for true 12-bit precision providing appropriate references are used and system noise levels permit. To improve performance in noisy conditions, it is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) and does so with zero switching overhead (that is, aggregate sampling bandwidth is equal to 806 ksps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is able to digitize the output of the on-board temperature sensor for calibration and other temperature-dependent functions. The SAR is not available in Deep Sleep and Hibernate modes as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

Figure 4. SAR ADC System Diagram



Two Opamps (CTBm Block)

PSoC 4100 has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, voltage buffers, filters, trans-impedance amplifiers, and other functions can be realized with external passives saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the S/H circuit of the ADC without requiring external buffering.

Temperature Sensor

PSoC 4100 has one on-chip temperature sensor This consists of a diode, which is biased by a current source that can be disabled to save power. The temperature sensor is connected to the ADC, which digitizes the reading and produces a temperature value using Cypress supplied software that includes calibration and linearization.

Low-power Comparators

PSoC 4100 has a pair of low-power comparators, which can also operate in the Deep Sleep and Hibernate modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode (Hibernate) where the system wake-up circuit is activated by a comparator switch event.

Fixed Function Digital

Timer/Counter/PWM Block (TCPWM)

The TCPWM block consists of four 16-bit counters with user-programmable period length. There is a Capture register to record the count value at the time of an event (which may be an I/O event), a period register which is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals which are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as deadband programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an overcurrent state is indicated and the PWMs driving the FETs need to be shut off immediately with no time for software intervention.

Serial Communication Blocks (SCB)

The PSoC 4100 has two SCBs, which can each implement an I^2C, UART, or SPI interface.

I^2C Mode: The hardware I^2C block implements a full multi-master and slave interface (it is capable of multimaster arbitration). This block is capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. The FIFO mode is available in all channels and is very useful in the absence of DMA.

The I^2C peripheral is compatible with the I^2C Standard-mode, Fast-mode, and Fast-Mode Plus devices as defined in the NXP I^2C-bus specification and user manual (UM10204). The I^2C bus I/O is implemented with GPIO in open-drain modes. The I^2C bus uses open-drain drivers for clock and data with pull-up resistors on the bus for clock and data connected to all nodes. The required Rise and Fall times for different I^2C speeds are guaranteed by using appropriate pull-up resistor values depending on VDD, Bus Capacitance, and resistor tolerance. For detailed information on how to calculate the optimum pull-up resistor value for your design, refer to the UM10204 I2C bus specification and user manual (the latest revision is available at www.nxp.com).

PSoC 4100 is not completely compliant with the I^2C spec in the following respects:

- GPIO cells are not overvoltage-tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I^2C system.
- Fast-mode Plus has an I_{OL} specification of 20 mA at a V_{OL} of 0.4 V. The GPIO cells can sink a maximum of 8-mA I_{OL} with a V_{OL} maximum of 0.6 V.
- Fast-mode and Fast-mode Plus specify minimum Fall times, which are not met with the GPIO cell; Slow strong mode can help meet this spec depending on the Bus Load.
- When the SCB is an I^2C master, it interposes an IDLE state between NACK and Repeated Start; the I^2C spec defines Bus free as following a Stop condition so other Active Masters do not intervene but a Master that has just become activated may start an Arbitration cycle.
- When the SCB is in I^2C slave mode, and Address Match on External Clock is enabled (EC_AM = 1) along with operation in the internally clocked mode (EC_OP = 0), then its I^2C address must be even.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (essentially adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

GPIO

PSoC 4100 has 36 GPIOs. The GPIO block implements the following:

- Eight drive strength modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes.
- Hold mode for latching previous state (used for retaining I/O state in Deep Sleep mode and Hibernate modes).
- Selectable slew rates for dV/dt related noise control to improve EMI.

The pins are organized in logical entities called ports, which are 8-bit in width. During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin. Pin locations for fixed-function peripherals are also fixed to reduce internal multiplexing complexity.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves. Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4100 since it has 4.5 ports).

Special Function Peripherals

LCD Segment Drive

PSoC 4100 has an LCD controller which can drive up to four commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as digital correlation and PWM.

Digital correlation pertains to modulating the frequency and levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays.

PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).

CapSense

CapSense is supported on all pins in the PSoC 4100 through a CapSense Sigma-Delta (CSD) block that can be connected to any pin through an analog mux bus that any GPIO pin can be connected to via an Analog switch. CapSense function can thus be provided on any pin or group of pins in a system under software control. A component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another mux bus to provide water tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input.

The CapSense block has two IDACs which can be used for general purposes if CapSense is not being used.(both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

WLCSP Package Bootloader

The WLCSP package is supplied with an I^2C Bootloader installed in flash. The bootloader is compatible with PSoC Creator bootloadable project files and has the following default settings:

- I^2C SCL and SDA connected to port pins P4.0 and P4.1 respectively (external pull-up resistors required)
- I^2C Slave mode, address 8, data rate = 100 kbps
- Single application
- Wait two seconds for bootload command
- Other bootloader options are as set by the PSoC Creator Bootloader Component default
- Occupies the bottom 4.5 K of flash

For more information on this bootloader, see the following Cypress application notes:

AN73854 - Introduction to Bootloaders

Note that a PSoC Creator bootloadable project must be associated with *.hex* and *.elf* files for a bootloader project that is configured for the target device. Bootloader *.hex* and *.elf* files can be found at http://www.cypress.com/?rID=78805. The factory-installed bootloader can be overwritten using JTAG or SWD programming.

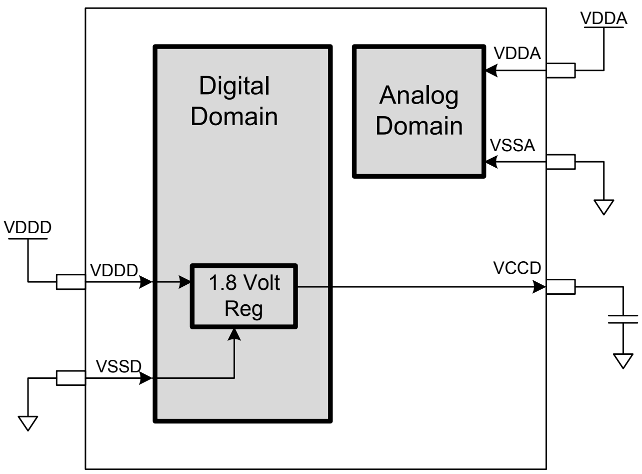
44-TQFP		40-QFN		28-SSOP		48-TQFP		Alternate Functions for Pins					Pin Description
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Analog	Alt 1	Alt 2	Alt 3	Alt 4	
24	P0.0	22	P0.0	19	P0.0	28	P0.0	comp1_inp	–	–	–	scb0_spi_ssel_1	Port 0 Pin 0: gpio, lcd, csd, scb0, comp
25	P0.1	23	P0.1	20	P0.1	29	P0.1	comp1_inn	–	–	–	scb0_spi_ssel_2	Port 0 Pin 1: gpio, lcd, csd, scb0, comp
26	P0.2	24	P0.2	21	P0.2	30	P0.2	comp2_inp	–	–	–	scb0_spi_ssel_3	Port 0 Pin 2: gpio, lcd, csd, scb0, comp
27	P0.3	25	P0.3	22	P0.3	31	P0.3	comp2_inn	–	–	–	–	Port 0 Pin 3: gpio, lcd, csd, comp
28	P0.4	26	P0.4	–	–	32	P0.4	–	–	scb1_uart_rx[1]	scb1_i2c_scl[1]	scb1_spi_mosi[1]	Port 0 Pin 4: gpio, lcd, csd, scb1
29	P0.5	27	P0.5	–	–	33	P0.5	–	–	scb1_uart_tx[1]	scb1_i2c_sda[1]	scb1_spi_miso[1]	Port 0 Pin 5: gpio, lcd, csd, scb1
30	P0.6	28	P0.6	23	P0.6	34	P0.6	–	ext_clk	–	–	scb1_spi_clk[1]	Port 0 Pin 6: gpio, lcd, csd, scb1, ext_clk
31	P0.7	29	P0.7	24	P0.7	35	P0.7	–	–	–	wakeup	scb1_spi_ssel_0[1]	Port 0 Pin 7: gpio, lcd, csd, scb1, wakeup
32	XRES	30	XRES	25	XRES	36	XRES	–	–	–	–	–	Chip reset, active low
33	VCCD	31	VCCD	26	VCCD	37	VCCD	–	–	–	–	–	Regulated supply, connect to 1µF cap or 1.8V
–	–	–	–	–	–	38	VSSD	–	–	–	–	–	Digital Ground
34	VDDD	32	VDDD	27	VDD	39	VDDD	–	–	–	–	–	Digital Supply, 1.8 - 5.5V
35	VDDA	33	VDDA	27	VDD	40	VDDA	–	–	–	–	–	Analog Supply, 1.8 - 5.5V, equal to VDDD
36	VSSA	34	VSSA	28	VSS	41	VSSA	–	–	–	–	–	Analog Ground
37	P1.0	35	P1.0	1	P1.0	42	P1.0	ctb.oa0.inp	tcpwm2_p[1]	–	–	–	Port 1 Pin 0: gpio, lcd, csd, ctb, pwm
38	P1.1	36	P1.1	2	P1.1	43	P1.1	ctb.oa0.inm	tcpwm2_n[1]	–	–	–	Port 1 Pin 1: gpio, lcd, csd, ctb, pwm
39	P1.2	37	P1.2	3	P1.2	44	P1.2	ctb.oa0.out	tcpwm3_p[1]	–	–	–	Port 1 Pin 2: gpio, lcd, csd, ctb, pwm
40	P1.3	38	P1.3	–	–	45	P1.3	ctb.oa1.out	tcpwm3_n[1]	–	–	–	Port 1 Pin 3: gpio, lcd, csd, ctb, pwm
41	P1.4	39	P1.4	–	–	46	P1.4	ctb.oa1.inm	–	–	–	–	Port 1 Pin 4: gpio, lcd, csd, ctb
42	P1.5	–	–	–	–	47	P1.5	ctb.oa1.inp	–	–	–	–	Port 1 Pin 5: gpio, lcd, csd, ctb
43	P1.6	–	–	–	–	48	P1.6	ctb.oa0.inp_alt	–	–	–	–	Port 1 Pin 6: gpio, lcd, csd
44	P1.7/VREF	40	P1.7/VREF	4	P1.7/VREF	1	P1.7/VREF	ctb.oa1.inp_alt ext_vref	–	–	–	–	Port 1 Pin 7: gpio, lcd, csd, ext_ref

Notes:
1. tcpwm_p and tcpwm_n refer to tcpwm non-inverted and inverted outputs respectively.
2. P3.2 and P3.3 are SWD pins after boot (reset).

Power

The following power system diagrams show the minimum set of power supply pins as implemented for PSoC 4100. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DDA} input. There are separate regulators for the Deep Sleep and Hibernate (lowered power supply and retention) modes. There is a separate low-noise regulator for the bandgap. The supply voltage range is 1.71 V to 5.5 V with all functions and circuits operating over that range.

Figure 10. PSoC 4 Power Supply



The PSoC 4100 family allows two distinct modes of power supply operation: Unregulated External Supply, and Regulated External Supply modes.

Unregulated External Supply

In this mode, PSoC 4100 is powered by an external power supply that can be anywhere in the range of 1.8 V to 5.5 V. This range is also designed for battery-powered operation, for instance, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of PSoC 4100 supplies the internal logic and the V_{CCD} output of the PSoC 4100 must be bypassed to ground via an external Capacitor (in the range of 1 µF to 1.6 µF; X5R ceramic or better).

V_{DDA} and V_{DDD} must be shorted together; the grounds, VSSA and V_{SS} must also be shorted together. Bypass capacitors must be used from V_{DDD} to ground, typical practice for systems in this frequency range is to use a capacitor in the 1-µF range in parallel with a smaller capacitor (0.1 µF for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the Bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

Figure 11. 48-TQFP Package Example

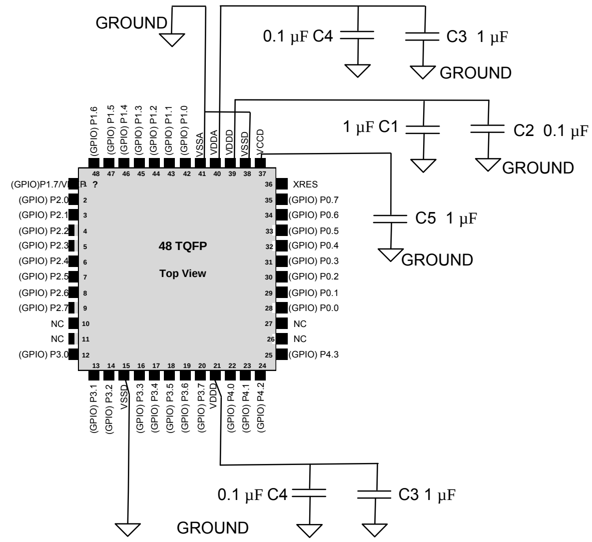
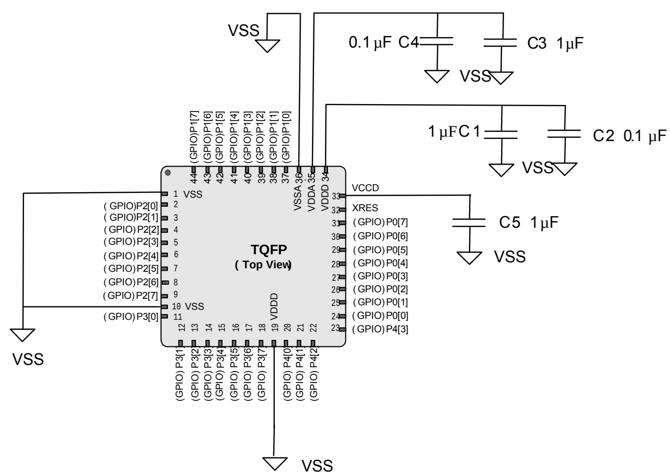


Figure 12. 44-TQFP Package Example



Power Supply	Bypass Capacitors
VDDD–VSS	0.1 µF ceramic at each pin (C2, C6) plus bulk capacitor 1 to 10 µF (C1). Total capacitance may be greater than 10 µF.
VDDA–VSSA	0.1 µF ceramic at pin (C4). Additional 1 µF to 10 µF (C3) bulk capacitor. Total capacitance may be greater than 10 µF.
VCCD–VSS	1 µF ceramic capacitor at the VCCD pin (C5)
VREF–VSSA (optional)	The internal bandgap may be bypassed with a 1 µF to 10 µF capacitor. Total capacitance may be greater than 10 µF.

Electrical Specifications

Absolute Maximum Ratings

Table 1. Absolute Maximum Ratings[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID1	V_{DDD_ABS}	Digital supply relative to V_{SSD}	–0.5	–	6	V	Absolute max
SID2	V_{CCD_ABS}	Direct digital core voltage input relative to Vssd	–0.5	–	1.95	V	Absolute max
SID3	V_{GPIO_ABS}	GPIO voltage	–0.5	–	V_{DD}+0.5	V	Absolute max
SID4	I_{GPIO_ABS}	Maximum current per GPIO	–25	–	25	mA	Absolute max
SID5	$I_{GPIO\_injection}$	GPIO injection current, Max for V_{IH} > V_{DDD}, and Min for V_{IL} < V_{SS}	–0.5	–	0.5	mA	Absolute max, current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	–	–	V	
BID45	ESD_CDM	Electrostatic discharge charged device model	500	–	–	V	
BID46	LU	Pin current for latch-up	–200	–	200	mA	

Device-Level Specifications

All specifications are valid for -40 °C ≤ TA ≤ 105 °C and TJ ≤ 125 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 2. DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID53	V_{DD}	Power Supply Input Voltage (V_{DDA} = V_{DDD} = V_{DD})	1.8	–	5.5	V	With regulator enabled
SID255	V_{DDD}	Power Supply Input Voltage unregulated	1.71	1.8	1.89	V	Internally unregulated Supply
SID54	V_{CCD}	Output voltage (for core logic)	–	1.8	–	V	
SID55	CEFC	External Regulator voltage bypass	1	1.3	1.6	µF	X5R ceramic or better
SID56	CEXC	Power supply decoupling capacitor	–	1	–	µF	X5R ceramic or better
Active Mode, V_{DD} = 1.71 V to 5.5 V. Typical Values measured at V_{DD} = 3.3 V							
SID9	IDD4	Execute from Flash; CPU at 6 MHz	–	–	2.8	mA	
SID10	IDD5	Execute from Flash; CPU at 6 MHz	–	2.2	–	mA	T = 25 °C
SID12	IDD7	Execute from Flash; CPU at 12 MHz,	–	–	4.2	mA	
SID13	IDD8	Execute from Flash; CPU at 12 MHz	–	3.7	–	mA	T = 25 °C
SID16	IDD11	Execute from Flash; CPU at 24 MHz	–	6.7	–	mA	T = 25 °C
SID17	IDD12	Execute from Flash; CPU at 24 MHz	–	–	7.2	mA	
Sleep Mode, V_{DD} = 1.7 V to 5.5 V							
SID25	IDD20	I^2C wakeup, WDT, and Comparators on. 6 MHz.	–	1.3	1.8	mA	V_{DD} = 1.71 to 5.5 V
SID25A	IDD20A	I^2C wakeup, WDT, and Comparators on. 12 MHz.	–	1.7	2.2	mA	V_{DD} = 1.71 to 5.5 V
Deep Sleep Mode, V_{DD} = 1.8 V to 3.6 V (Regulator on)							
SID31	IDD26	I^2C wakeup and WDT on.	–	1.3	–	µA	T = 25 °C
SID32	IDD27	I^2C wakeup and WDT on.	–	–	45	µA	T = 85 °C

Note

1. Usage above the absolute maximum conditions listed in Table 1 may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

Table 2. DC Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
Deep Sleep Mode, V_{DD} = 3.6 V to 5.5 V							
SID34	IDD29	I^2C wakeup and WDT on	–	1.5	15	µA	Typ at 25 °C Max at 85 °C
Deep Sleep Mode, V_{DD} = 1.71 V to 1.89 V (Regulator bypassed)							
SID37	IDD32	I^2C wakeup and WDT on.	–	1.7	–	µA	T = 25 °C
SID38	IDD33	I^2C wakeup and WDT on	–	–	60	µA	T = 85 °C
Deep Sleep Mode, +105 °C							
SID33Q	IDD28Q	I^2C wakeup and WDT on. Regulator Off.	–	–	135	µA	V_{DD} = 1.71 to 1.89
SID34Q	IDD29Q	I^2C wakeup and WDT on.	–	–	180	µA	V_{DD} = 1.8 to 3.6
SID35Q	IDD30Q	I^2C wakeup and WDT on.	–	–	140	µA	V_{DD} = 3.6 to 5.5
Hibernate Mode, V_{DD} = 1.8 V to 3.6 V (Regulator on)							
SID40	IDD35	GPIO and Reset active	–	150	–	nA	T = 25 °C
SID41	IDD36	GPIO and Reset active	–	–	1000	nA	T = 85 °C
Hibernate Mode, V_{DD} = 3.6 V to 5.5 V							
SID43	IDD38	GPIO and Reset active	–	150	–	nA	T = 25 °C
Hibernate Mode, V_{DD} = 1.71 V to 1.89 V (Regulator bypassed)							
SID46	IDD41	GPIO and Reset active	–	150	–	nA	T = 25 °C
SID47	IDD42	GPIO and Reset active	–	–	1000	nA	T = 85 °C
Hibernate Mode, +105 °C							
SID42Q	IDD37Q	Regulator Off	–	–	19.4	µA	V_{DD} = 1.71 to 1.89
SID43Q	IDD38Q		–	–	17	µA	V_{DD} = 1.8 to 3.6
SID44Q	IDD39Q		–	–	16	µA	V_{DD} = 3.6 to 5.5
Stop Mode							
SID304	IDD43A	Stop Mode current; V_{DD} = 3.3 V	–	20	80	nA	Typ at 25 °C Max at 85 °C
Stop Mode, +105 °C							
SID304Q	IDD43AQ	Stop Mode current; V_{DD} = 3.6 V	–	–	5645	nA	
XRES current							
SID307	IDD_XR	Supply current while XRES asserted	–	2	5	mA	

Table 3. AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F_{CPU}	CPU frequency	DC	–	24	MHz	$1.71 \le V_{DD} \le 5.5$
SID49	T_{SLEEP}	Wakeup from sleep mode	–	0	–	µs	Guaranteed by characterization
SID50	$T_{DEEPSLEEP}$	Wakeup from Deep Sleep mode	–	–	25	µs	24-MHz IMO. Guaranteed by characterization
SID51	$T_{HIBERNATE}$	Wakeup from Hibernate and Stop modes	–	–	2	ms	Guaranteed by characterization
SID52	$T_{RESETWIDTH}$	External reset pulse width	1	–	–	µs	Guaranteed by characterization

GPIO

Table 4. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	V_{IH}[2]	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID58	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}	V	CMOS Input
SID241	V_{IH}[2]	LVTTL input, V_{DDD} < 2.7 V	0.7× V_{DDD}	–	–	V	
SID242	V_{IL}	LVTTL input, V_{DDD} < 2.7 V	–	–	0.3 × V_{DDD}	V	
SID243	V_{IH}[2]	LVTTL input, $V_{DDD} \geq$ 2.7 V	2.0	–	–	V	
SID244	V_{IL}	LVTTL input, $V_{DDD} \geq$ 2.7 V	–	–	0.8	V	
SID59	V_{OH}	Output voltage high level	V_{DDD} –0.6	–	–	V	I_{OH} = 4 mA at 3-V V_{DDD}
SID60	V_{OH}	Output voltage high level	V_{DDD} –0.5	–	–	V	I_{OH} = 1 mA at 1.8-V V_{DDD}
SID61	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 4 mA at 1.8-V V_{DDD}
SID62	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 8 mA at 3-V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4	V	I_{OL} = 3 mA at 3-V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DDD} = 3.0-V
SID65A	I_{IL_CTBM}	Input leakage current (absolute value) for CTBM pins	–	–	4	nA	
SID66	C_{IN}	Input capacitance	–	–	7	pF	
SID67	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq$ 2.7 V. Guaranteed by characterization
SID68	$V_{HYSCMOS}$	Input hysteresis CMOS	0.05 × V_{DDD}	–	–	mV	Guaranteed by characterization
SID69	I_{DIODE}	Current through protection diode to V_{DD}/Vss	–	–	100	µA	Guaranteed by characterization
SID69A	I_{TOT_GPIO}	Maximum Total Source or Sink Chip Current	–	–	200	mA	Guaranteed by characterization

Note
2. V_{IH} must not exceed V_{DDD} + 0.2 V.

Table 5. GPIO AC Specifications (Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3-V V_{DDD}, Cload = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12	ns	3.3-V V_{DDD}, Cload = 25 pF
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60	ns	3.3-V V_{DDD}, Cload = 25 pF
SID73	T_{FALLS}	Fall time in slow strong mode	10	–	60	ns	3.3-V V_{DDD}, Cload = 25 pF
SID74	$F_{GPIOUT1}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Fast strong mode.	–	–	24	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID75	$F_{GPIOUT2}$	GPIO Fout;1.7 V≤ V_{DDD}≤ 3.3 V. Fast strong mode.	–	–	16.7	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID76	$F_{GPIOUT3}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Slow strong mode.	–	–	7	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID245	$F_{GPIOUT4}$	GPIO Fout;1.7 V ≤ V_{DDD} ≤ 3.3 V. Slow strong mode.	–	–	3.5	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID246	F_{GPIOIN}	GPIO input operating frequency; 1.71 V ≤ V_{DDD} ≤ 5.5 V	–	–	24	MHz	90/10% V_{IO}

XRES

Table 6. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	V_{IH}	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}	V	CMOS Input
SID79	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID80	C_{IN}	Input capacitance	–	3	–	pF	
SID81	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Guaranteed by characterization
SID82	I_{DIODE}	Current through protection diode to V_{DDD}/V_{SS}	–	–	100	µA	Guaranteed by characterization

Table 7. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	µs	Guaranteed by characterization

CSD

Table 14. CSD Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID.CSD#16	IDAC1IDD	IDAC1 (8 bits) block current	–	–	1125	µA	
SID.CSD#17	IDAC2IDD	IDAC2 (7 bits) block current	–	–	1125	µA	
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	
SID308A	VCOMPIDAC	Voltage compliance range of IDAC for S0	0.8	–	V_{DD}-0.8	V	
SID309	IDAC1	DNL for 8-bit resolution	–1	–	1	LSB	
SID310	IDAC1	INL for 8-bit resolution	–3	–	3	LSB	
SID311	IDAC2	DNL for 7-bit resolution	–1	–	1	LSB	
SID312	IDAC2	INL for 7-bit resolution	–3	–	3	LSB	
SID313	SNR	Ratio of counts of finger to noise, 0.1-pF sensitivity	5	–	–	Ratio	Capacitance range of 9 to 35 pF, 0.1-pF sensitivity
SID314	IDAC1_CRT1	Output current of IDAC1 (8 bits) in High range	–	612	–	uA	
SID314A	IDAC1_CRT2	Output current of IDAC1 (8 bits) in Low range	–	306	–	uA	
SID315	IDAC2_CRT1	Output current of IDAC2 (7 bits) in High range	–	304.8	–	uA	
SID315A	IDAC2_CRT2	Output current of IDAC2 (7 bits) in Low range	–	152.4	–	uA	
SID320	IDACOFFSET	All zeroes input	–	–	±1	LSB	
SID321	IDACGAIN	Full-scale error less offset	–	–	±10	%	
SID322	IDACMISMATCH	Mismatch between IDACs	–	–	7	LSB	
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor	–	2.2	–	nF	5-V rating, X7R or NP0 cap.

Voltage Monitors

Table 30. Voltage Monitors DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID195	V_{LVI1}	LVI_A/D_SEL[3:0] = 0000b	1.71	1.75	1.79	V	
SID196	V_{LVI2}	LVI_A/D_SEL[3:0] = 0001b	1.76	1.80	1.85	V	
SID197	V_{LVI3}	LVI_A/D_SEL[3:0] = 0010b	1.85	1.90	1.95	V	
SID198	V_{LVI4}	LVI_A/D_SEL[3:0] = 0011b	1.95	2.00	2.05	V	
SID199	V_{LVI5}	LVI_A/D_SEL[3:0] = 0100b	2.05	2.10	2.15	V	
SID200	V_{LVI6}	LVI_A/D_SEL[3:0] = 0101b	2.15	2.20	2.26	V	
SID201	V_{LVI7}	LVI_A/D_SEL[3:0] = 0110b	2.24	2.30	2.36	V	
SID202	V_{LVI8}	LVI_A/D_SEL[3:0] = 0111b	2.34	2.40	2.46	V	
SID203	V_{LVI9}	LVI_A/D_SEL[3:0] = 1000b	2.44	2.50	2.56	V	
SID204	V_{LVI10}	LVI_A/D_SEL[3:0] = 1001b	2.54	2.60	2.67	V	
SID205	V_{LVI11}	LVI_A/D_SEL[3:0] = 1010b	2.63	2.70	2.77	V	
SID206	V_{LVI12}	LVI_A/D_SEL[3:0] = 1011b	2.73	2.80	2.87	V	
SID207	V_{LVI13}	LVI_A/D_SEL[3:0] = 1100b	2.83	2.90	2.97	V	
SID208	V_{LVI14}	LVI_A/D_SEL[3:0] = 1101b	2.93	3.00	3.08	V	
SID209	V_{LVI15}	LVI_A/D_SEL[3:0] = 1110b	3.12	3.20	3.28	V	
SID210	V_{LVI16}	LVI_A/D_SEL[3:0] = 1111b	4.39	4.50	4.61	V	
SID211	LVI_IDD	Block current	–	–	100	µA	Guaranteed by characterization

Table 31. Voltage Monitors AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID212	$T_{MONTRIP}$	Voltage monitor trip time	–	–	1	µs	Guaranteed by characterization

SWD Interface

Table 32. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCLK1	$3.3\ V \le V_{DD} \le 5.5\ V$	–	–	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71\ V \le V_{DD} \le 3.3\ V$	–	–	7	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	T = 1/f SWDCLK	–	–	0.5*T	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	T = 1/f SWDCLK	1	–	–	ns	Guaranteed by characterization

Part Numbering Conventions

PSoC 4 devices follow the part numbering convention described in the following table. All fields are single-character alphanumeric (0, 1, 2, …, 9, A,B, …, Z) unless stated otherwise.

The part numbers are of the form CY8C4ABCDEF-XYZ where the fields are defined as follows.

Example — CY8C 4 A B C D E F - X Y Z

Example	
	Cypress Prefix (CY8C)
4 : PSoC 4	Architecture (4)
1 : 4100Family	Family within Architecture (A)
2 : 24 MHz	Speed Grade (B)
5 : 32 KB	Flash Capacity (C)
AX : TQFP	Package Code (D E)
I : Industrial	Temperature Range (F)
	Attributes Set (X Y Z)

The Field Values are listed in the following table.

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family within architecture	1	4100 Family
		2	4200 Family
B	CPU Speed	2	24 MHz
		4	48 MHz
C	Flash Capacity	4	16 KB
		5	32 KB
DE	Package Code	AX, AZ	TQFP
		LQ	QFN
		PV	SSOP
		FN	WLCSP
F	Temperature Range	I	Industrial
		Q	Extended Industrial
XYZ	Attributes Code	000-999	Code of feature set in specific family

Figure 15. 28-pin (210-mil) SSOP Package Outline

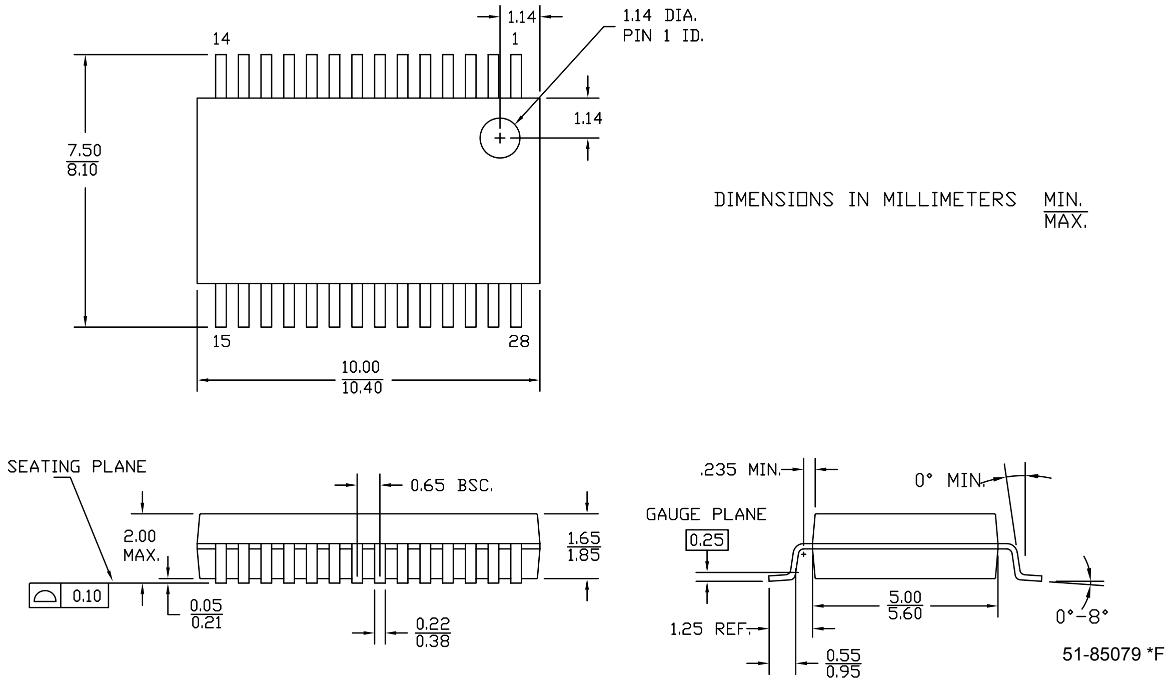
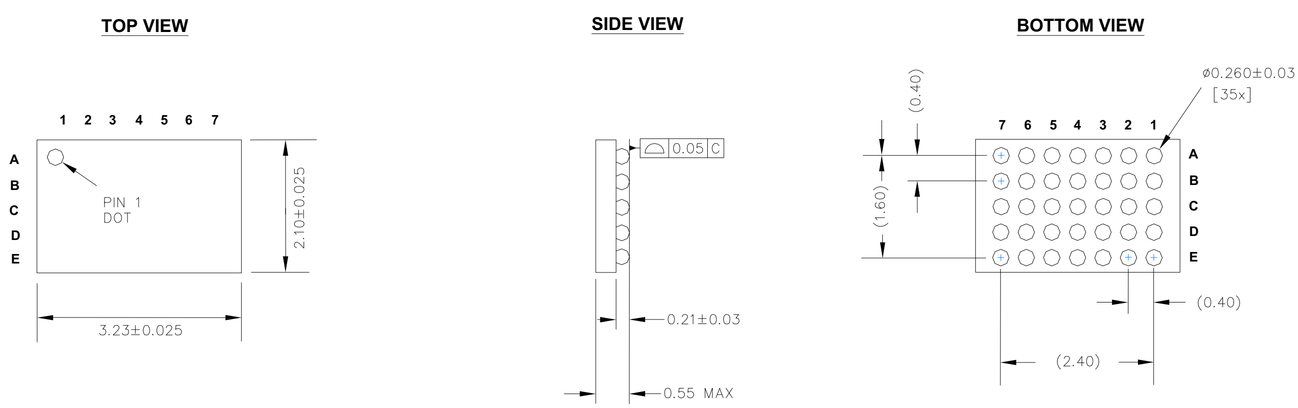


Figure 16. 35-ball WLCSP Package Outline



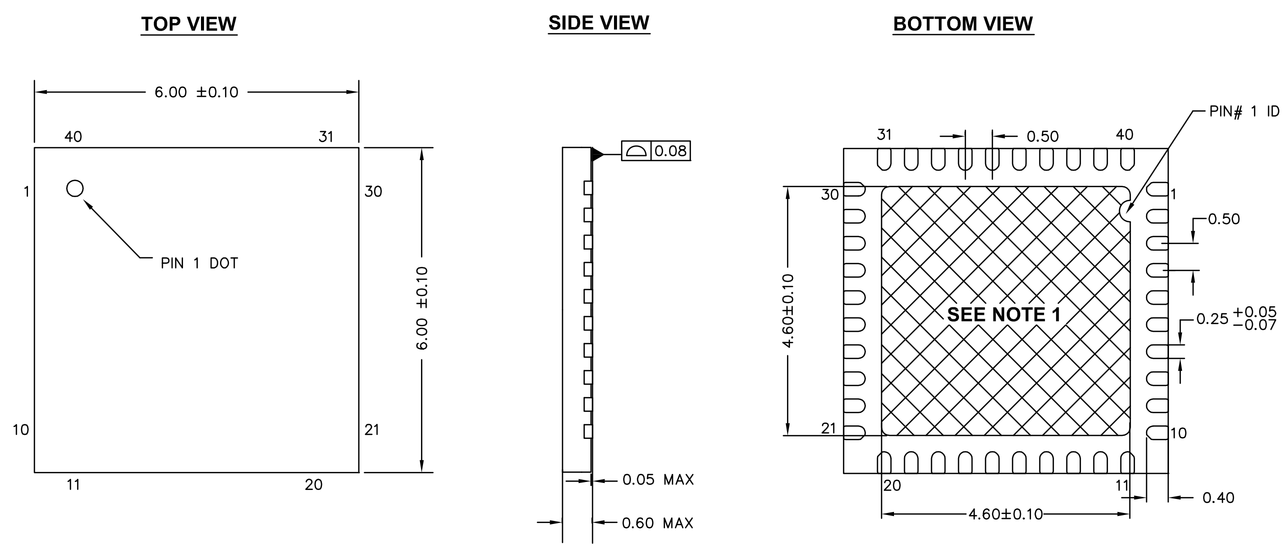
NOTES:

1. REFERENCE JEDEC PUBLICATION 95, DESIGN GUIDE 4.18

2. ALL DIMENSIONS ARE IN MILLIMETERS

001-93741 **

Figure 17. 40-pin QFN Package Outline



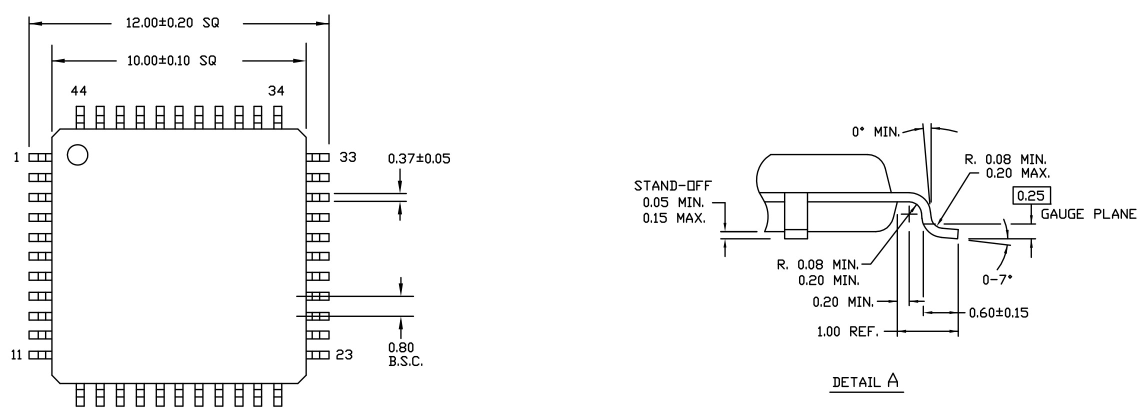
NOTES:

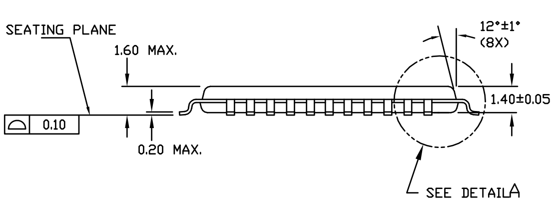
1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT: 68 ±2 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 *A

The center pad on the QFN package should be connected to ground (VSS) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floating and not connected to any other signal.

Figure 18. 44-pin TQFP Package Outline



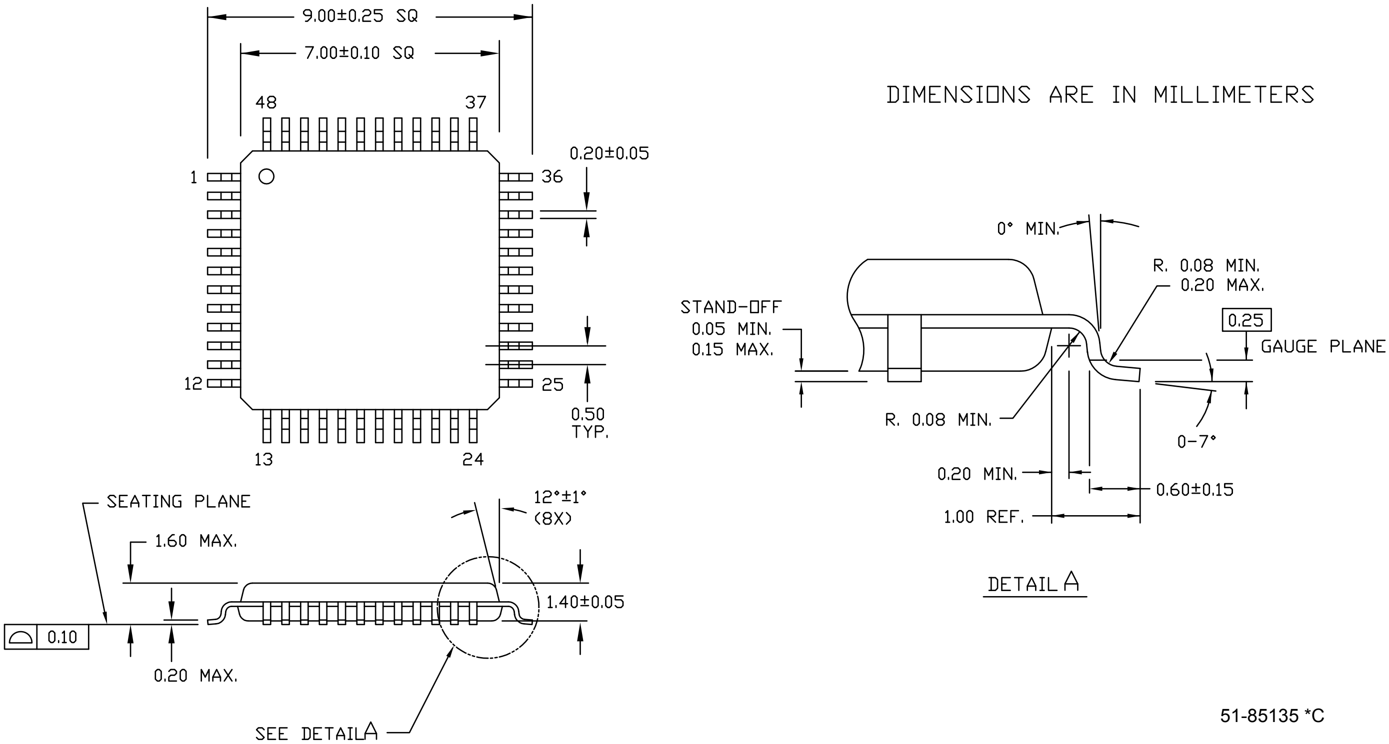


NOTE:

1. JEDEC STD REF MS-026
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
   MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE
   BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
3. DIMENSIONS IN MILLIMETERS

51-85064 *G

Figure 19. 48-Pin TQFP Package Outline



51-85135 *C

Table 43. Acronyms Used in this Document *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I^2C serial clock
SDA	I^2C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

Table 43. Acronyms Used in this Document *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Document Conventions

Units of Measure

Table 44. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µV	microvolt
µW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

Revision History

Description Title: PSoC® 4: PSoC 4100 Family Datasheet Programmable System-on-Chip (PSoC®) Document Number:001-87220				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
*B	4108562	WKA	08/29/2013	Added clarifying note about the XRES pin in the Reset section. Added a link reference to the PSoC 4 TRM. Updated the footnote in Absolute Maximum Ratings. Updated Sleep Mode IDD specs in DC Specifications. Updated Comparator DC Specifications Updated SAR ADC AC Specifications (Guaranteed by Characterization) Updated LCD Direct Drive DC Specifications (Guaranteed by Characterization) Updated the number of GPIOs in Ordering Information.
*C	4568937	WKA	11/19/2014	Added 48-pin TQFP pin and package details. Added SID308A spec details. Updated Ordering Information.
*D	4617283	WKA	01/08/2015	Corrected typo in the ordering information table. Updated 28-pin SSOP package diagram.
*E	4643655	WKA	04/29/2015	Added 35 WLCSP pinout and package detail information. Updated CSD specifications.
*F	5287114	WKA	06/09/2016	Corrected typo in the Features section. Added reference to AN90071 in the More Information section. Updated Flash section with details of flash protection modes. Added notes in the Pinouts section. Updated 40-pin QFN and 28-pin SSOP pin diagrams. Added PSoC 4 Power Supply diagram. Updated the Bypass Capacitors column in the Power Supply table. Updated values for SID32, SID34, SID38, SID269, SID270, SID271. Added SID299A. Updated Comparator Specifications. Updated TCPWM Specifications. Updated values for SID149, SID160, SID171. Updated Conditions for SID190. Added BID55. Removed Conditions for SID237. Added reference to PSoC 4 CAB Libraries with Schematics Symbols and PCB Footprints in the Packaging section.
*G	5327384	WKA	06/28/2016	Removed the capacitor connection for Pin 15 in Figure 11.
*H	5704046	GNKK	04/26/2017	Updated the Cypress logo and copyright information.